

## ABSTRACT

5 A rectangular frame-like auxiliary  
substrate for hierarchical mounting 14 is mounted so  
as to surround a semiconductor component 15 mounted  
on a printed wiring board 11, and another  
semiconductor component 16 is mounted above the  
semiconductor component 15, being supported on the  
auxiliary substrate for hierarchical mounting 14  
10 with terminals of the semiconductor component 16  
being connected thereto. The auxiliary substrate  
for hierarchical mounting 14 has wiring patterns 35a  
and through holes 34a, and includes a power supply  
layer 32 and a ground layer 33 inside thereof with  
15 printed wiring board pads on a lower surface of the  
auxiliary substrate for hierarchical mounting 14  
being more dispersed than component pads 23a on an  
upper surface of the auxiliary substrate for  
hierarchical mounting 14. Therefore, a gap space 41  
20 between each adjacent ones of pads 40a on the  
printed wiring board 11 which gap space 41  
corresponds to the semiconductor component 16 is  
widened so that a wiring pattern 43 extending  
outward on the printed wiring board from a pad 21a  
25 connected to the semiconductor component 15 passes  
through the gap space 41 without difficulty.